US00D586812S

(12) United States Design Patent
Guenther

(10) **Patent No.: US D586,812 S**
(45) **Date of Patent: ** Feb. 17, 2009**

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(54) **ELECTRONIC SIGNATURE PAD**

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(73) Assignee: **StepOver GmbH**, Stuttgart (DE)

(**) Term: **14 Years**

(21) Appl. No.: **29/293,029**

(22) Filed: **Nov. 7, 2007**

(30) **Foreign Application Priority Data**

May 8, 2007 (DE) 4 07 02 450

(51) **LOC (9) Cl.** **14-02**
(52) **U.S. Cl.** **D14/383**
(58) **Field of Classification Search** D14/341–346, D14/383–387; D18/4.4, 4.6, 6, 7; 382/115, 382/116, 119, 124, 126; 346/71; 235/382, 235/382.5; 345/169, 173; 361/681–686
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D307,134	S *	4/1990	Makidera	D14/342
5,103,486	A *	4/1992	Grippi	382/116
5,375,226	A	12/1994	Sano et al.	
6,177,926	B1	1/2001	Kunert	
6,757,156	B2 *	6/2004	Adams et al.	361/681
D532,009	S *	11/2006	Zank et al.	D14/342
2002/0129257	A1	9/2002	Parmelee et al.	
2003/0132918	A1 *	7/2003	Fitch et al.	345/173

FOREIGN PATENT DOCUMENTS

CA	2 373 220	A1	11/2000
DE	198 11 930	A1	9/1999
DE	198 59 932	A1	6/2000
DE	10 2006 000 859	A1	7/2007

OTHER PUBLICATIONS

http://www.interlinkelectronics.com/library/media/papers/pdf/ePad%20family%20Brochure%202006.pdf, Interlink Electronics, Inc., pp. 1-4, 2007, Camarillo, CA 93012.
http://www.topazsystems.com/products/specs/SigGemColor57.pdf, Topaz Systems, Inc., pp. 1-2, 2003-2006, Simi Valley, CA 93065.
http://www.topazsystems.com/products/index.htm, Electronic signature pad options, p. 1, 2003-2005, Simi Valley, CA 93065.
U.S. Appl. No. 11/964,293, filed Dec. 26, 2007, Guenther.

* cited by examiner

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(57) **CLAIM**

The ornamental design for an electronic signature pad, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of an electronic signature pad of the present invention;

FIG. **2** is a front elevational view of the electronic signature pad;

FIG. **3** is a back elevational view of the electronic signature pad;

FIG. **4** is a top plan view of the electronic signature pad;

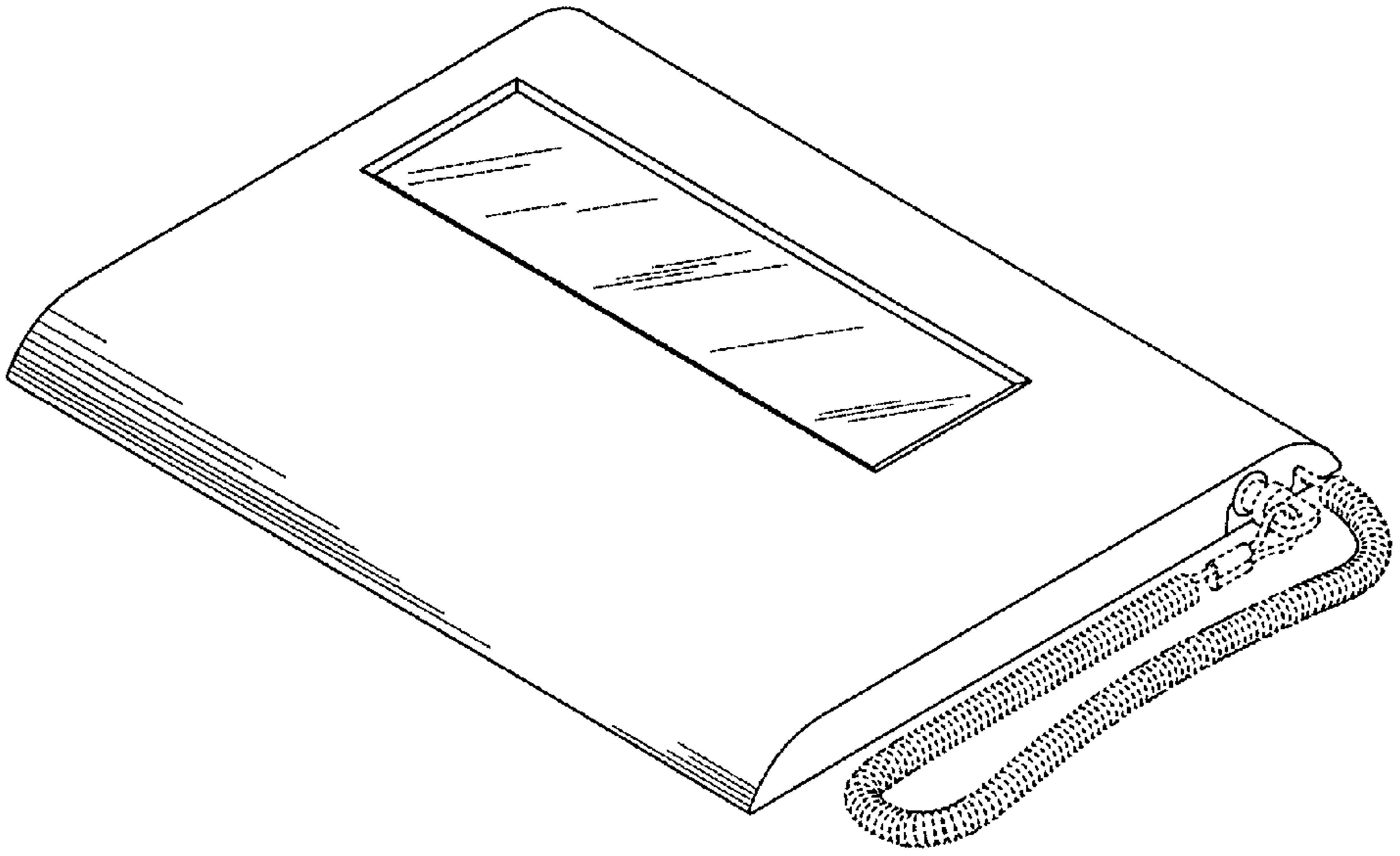
FIG. **5** is a bottom plan view of the electronic signature pad;

FIG. **6** is a right side elevational view of the electronic signature pad; and,

FIG. **7** is a left side elevational view of the electronic signature pad.

The broken lines shown are for illustrative purposes only and form no part of the claimed design.

1 Claim, 7 Drawing Sheets



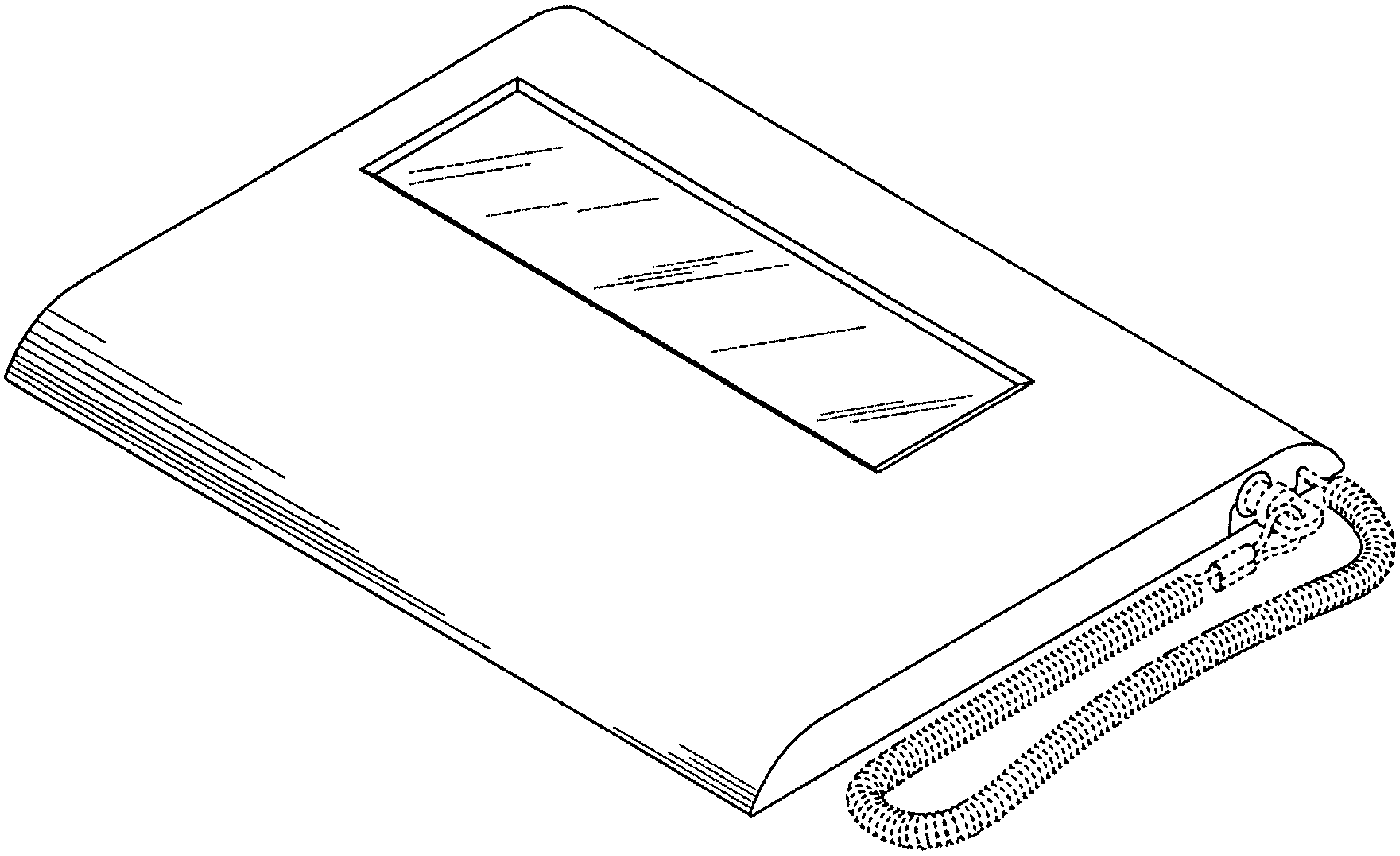


Fig. 1

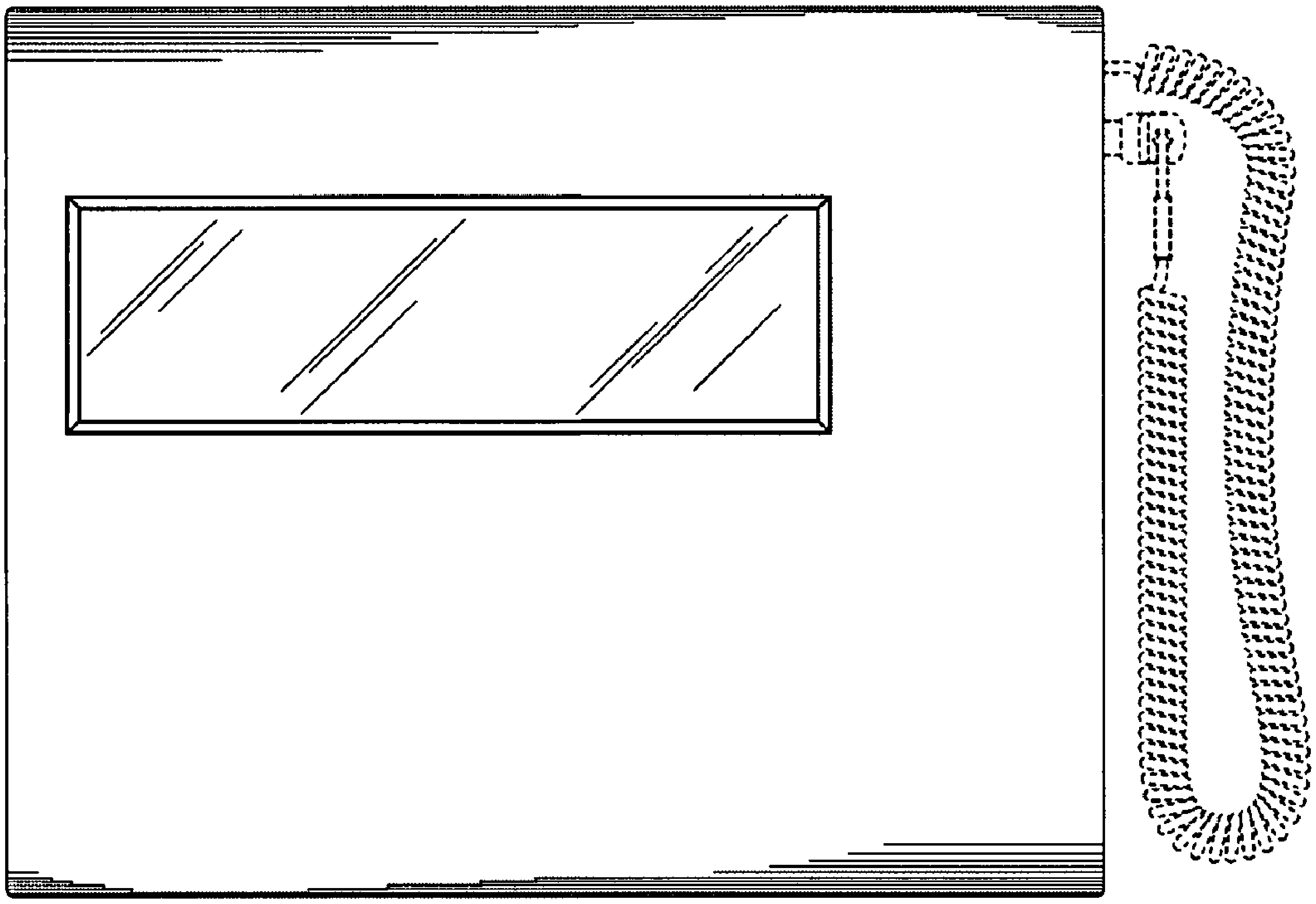


Fig. 2

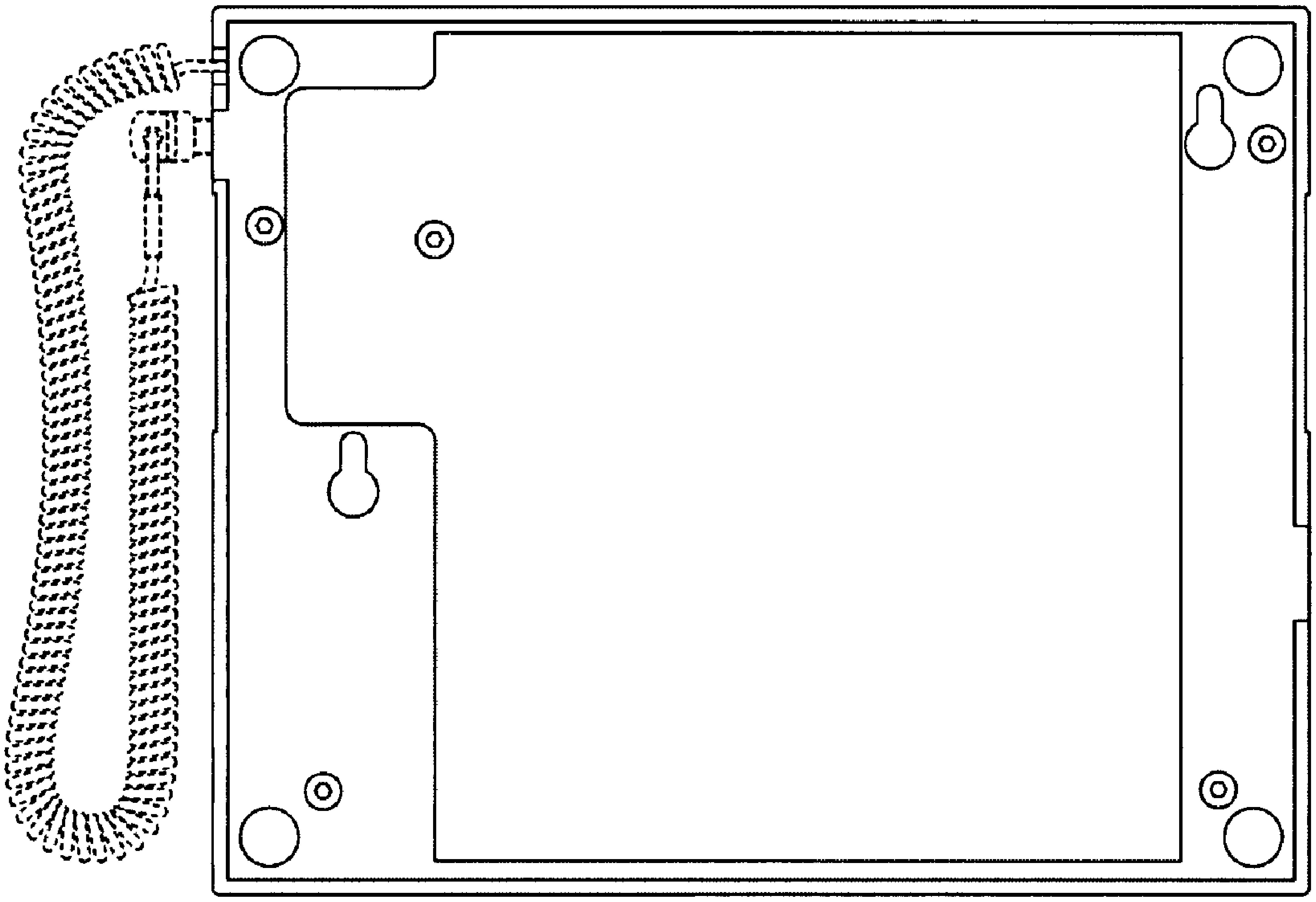


Fig. 3

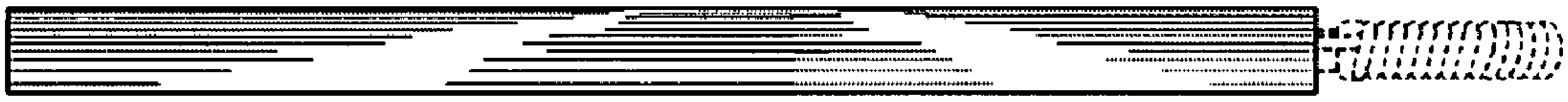


Fig. 4

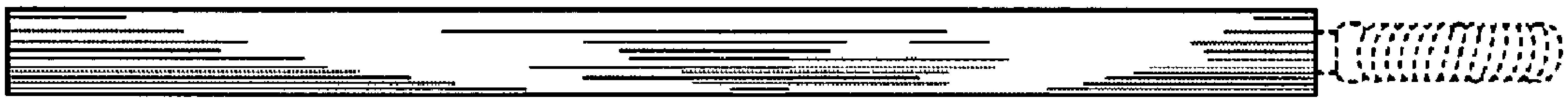


Fig. 5

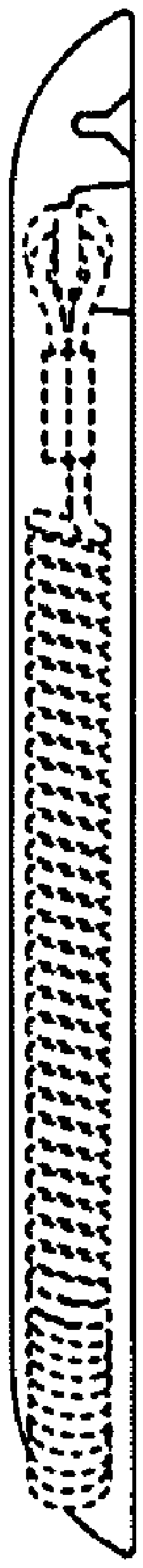


Fig. 6

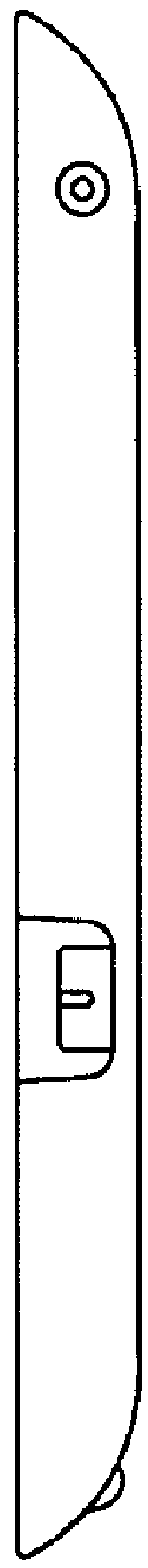


Fig. 7